


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L151RBT7A STM32L151RBT7ATR	S15W*429XXXY	A	998Z	2018-09-04
Amount	UoM	Unit type	ST ECOPACK Grade	
355.39	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
able; if coating is used or other bulk	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10X10X1.4	64	L Bend	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	S15W*429XXXY				5999999.0	0.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	9.883	mg	supplier	die	Silicon (Si)	7440-21-3		9.578	mg	969139	26951
				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	2732	76
				supplier	metallization	Copper (Cu)	7440-50-8		0.088	mg	8904	248
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.010	mg	1012	28
				supplier	metallization	Titanium (Ti)	7440-32-6		0.013	mg	1315	37
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	101	3
				supplier	Passivation	Silicon Nitride	12033-89-5		0.024	mg	2428	68
				supplier	Passivation	Silicon Oxide	7631-86-9		0.142	mg	14368	400
Die Attach Epoxy_ABLEBOND 3230_H	M-011 Other inorganic materials	0.908	mg	Supplier	Metals	Silver	7440-22-4		0.818	mg	901000	2302
				Supplier	Plastics/polymers	Highly cross-linked polymer	Proprietary		0.090	mg	99000	253
Mold Compound_EME-G631SHQ_Sur	M-011 Other inorganic materials	245.046	mg	Supplier	Plastics/polymers	Epoxy Resin A	Proprietary		5.213	mg	21000	14669
				Supplier	Plastics/polymers	Epoxy Resin B	Proprietary		5.213	mg	21000	14669
				Supplier	Plastics/polymers	Phenol Resin	Proprietary		13.902	mg	56000	39119
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		190.541	mg	780450	-463852
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		28.629	mg	115320	80556
Wire_AG Si TYPE_MKE	Bonding Wire	0.614	mg	Supplier	Non-metals	Carbon Black	1333-86-4		1.547	mg	6230	4352
				Supplier	Metals	Silver	7440-22-4		0.589	mg	960000	1658
Plating anode_Pure Tin_Nuo Nengda	M-011 Other inorganic materials	1.438	mg	Supplier	Metals	Others	Proprietary		0.025	mg	40000	69
				Supplier	Metals	Tin	7440-31-5		1.438	mg	1000000	4046
Leadframe_C194+Ag_HDS	Copper & its alloys	97.500	mg	Supplier	Metals	Iron	7439-89-6		2.132	mg	21865	5999
				Supplier	Non-metals	Phosphorus	7723-14-0		0.071	mg	730	200
				Supplier	Metals	Zinc	7440-66-6		0.110	mg	1125	309
				Supplier	Metals	Copper	7440-50-8		89.040	mg	913235	250544
				Supplier	Metals	Silver	7440-22-4		6.143	mg	63000	17284
				JIG-R	Metals	Lead	7439-92-1		0.004	mg	45	12